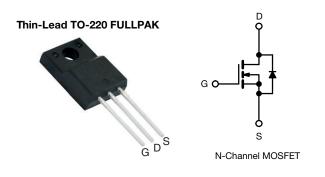
Vishay Siliconix

www.vishay.com

EL Series Power MOSFET



PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	650				
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 V$	0.155			
Q _g max. (nC)	82				
Q _{gs} (nC)	20				
Q _{gd} (nC)	13				
Configuration	Single				

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
- Welding
- Induction heating
- Motor drives
- Battery chargers
- Renewable energy
- Solar (PV inverters)

ORDERING INFORMATION				
Package	Thin-lead TO-220 FULLPAK			
Lead (Pb)-free and halogen-free	SiHA22N60AEL-GE3			

PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V _{DS}	600	v
Gate-source voltage	V _{GS}	± 30	v	
Continuous drain current (T _J = 150 °C) e	V_{GS} at 10 V $T_{C} = 25 °C$ $T_{C} = 100 °C$	Ι _D	21	А
	$T_{\rm C} = 100 ^{\circ}{\rm C}$		13	
Pulsed drain current ^a		I _{DM}	48	
Linear derating factor			1.7	W/°C
Single pulse avalanche energy ^b		E _{AS}	183	mJ
Maximum power dissipation		PD	35	W
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C
Reverse diode dv/dt d		dv/dt	50	V/ns
Soldering recommendations (peak temperature) ^c	For 10 s		260	°C

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature

- b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 3.6 A
- c. 1.6 mm from case
- d. $I_{SD} \leq I_D$, di/dt = 100 A/µs, starting T_J = 25 °C

e. Limited by maximum junction temperature

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RoHS COMPLIANT HALOGEN FREE



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PARAMETER	SYMBOL	TYP.		MAX.		UNIT		
Maximum junction-to-ambient	R _{thJA}	-		65 3.6		20.044		
Maximum junction-to-case (drain)	R _{thJC}	-				°C/W		
			•					
SPECIFICATIONS (T _J = 25 °C, u	nless otherwi	se noted)						
PARAMETER	SYMBOL	TES	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							•	
Drain-source breakdown voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 2	50 µA	600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_J$	Referenc	e to 25 °C,	l _D = 1 mA	-	0.68	-	V/°C
Gate-source threshold Voltage (N)	V _{GS(th)}	V _{DS} =	V _{GS} , I _D = 2	50 µA	2.0	-	4.0	V
		, ,	V _{GS} = ± 20 \	/	-	-	± 100	nA
Gate-source leakage	I _{GSS}	, N	$V_{GS} = \pm 30 \text{ V}$		-	-	± 1	μA
Zero gate voltage drain current		V _{DS} =	600 V, V _{GS}	= 0 V	-	-	1	
	I _{DSS}	V _{DS} = 480 V	, V _{GS} = 0 V,	T _J = 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V I _D = 11 A		-	0.155	0.180	Ω	
Forward transconductance	9 _{fs}	V _{DS} = 8 V, I _D = 11 A		-	16	-	S	
Dynamic							•	
Input capacitance	C _{iss}		V _{GS} = 0 V,		-	1757	-	
Output capacitance	C _{oss}	$V_{\text{DS}} = 100 \text{ V},$ f = 1 MHz		-	74	-	-	
Reverse transfer capacitance	C _{rss}			-	6	-		
Effective output capacitance, energy related ^a	C _{o(er)}	V_{DS} = 0 V to 480 V, V_{GS} = 0 V		-	48	-	pF	
Effective output capacitance, time related ^b	C _{o(tr)}			-	257	-		
Total gate charge	Qg				-	41	82	
Gate-source charge	Q _{gs}	$V_{GS} = 10 V$	I _D = 11 A	, V _{DS} = 480 V	-	10	-	nC
Gate-drain charge	Q _{gd}	1			-	13	-	1
Turn-on delay time	t _{d(on)}				-	27	54	
Rise time	t _r	V _{DD} =	V _{DD} = 480 V, I _D = 11 A,		-	24	48	1
Turn-off delay time	t _{d(off)}	$V_{GS} = 10 \text{ V}, \text{ R}_{g} = 9.1 \Omega$		-	86	172	ns	
Fall time	t _f			-	28	56	1	
Gate input resistance	Rg	f = 1 MHz, open drain		3.6	7.2	14.4	Ω	
Drain-Source Body Diode Characteristic	s							
Continuous source-drain diode current	I _S	MOSFET sym showing the	bol		-	-	21	
		intogral rovor	`	(i⊷ 本)	l	1	L	Δ

Continuous source-drain diode current	۱ _S	MOSFET symbol showing the integral reverse p - n junction diode	-	-	21	A
Pulsed diode forward current	I _{SM}		-	-	48	
Diode forward voltage	V _{SD}	$T_{J} = 25 \text{ °C}, I_{S} = 11 \text{ A}, V_{GS} = 0 \text{ V}$	-	-	1.2	V
Reverse recovery time	t _{rr}		-	285	570	ns
Reverse recovery charge	Q _{rr}	T _J = 25 °C, I _F = I _S = 11 A, di/dt = 100 A/μs, V _B = 400 V	-	4.1	8.2	μC
Reverse recovery current	I _{RRM}		-	27	-	Α

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

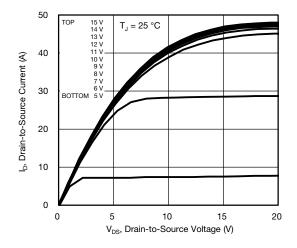
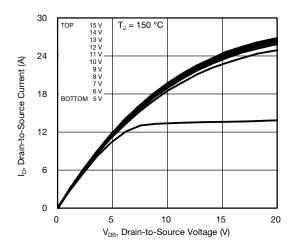
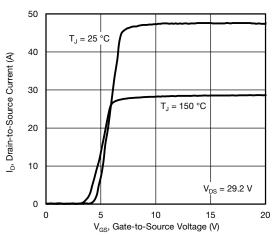


Fig. 1 - Typical Output Characteristics









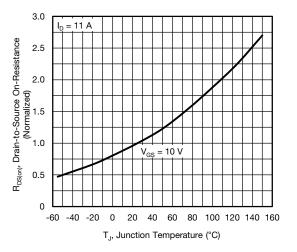


Fig. 4 - Normalized On-Resistance vs. Temperature

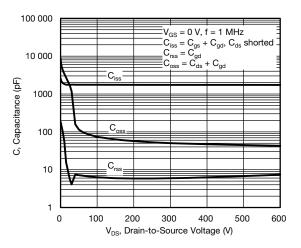


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

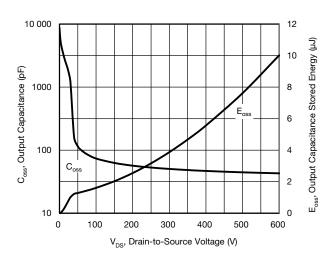


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}

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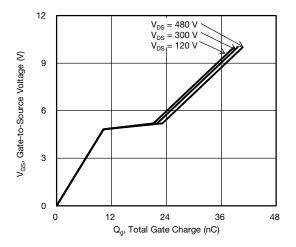


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

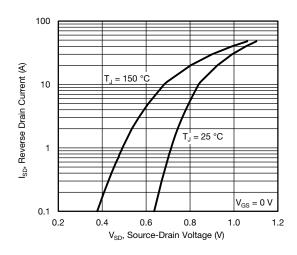


Fig. 8 - Typical Source-Drain Diode Forward Voltage

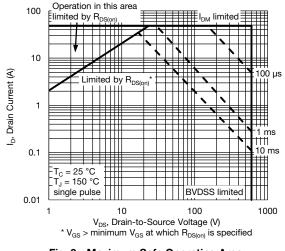


Fig. 9 - Maximum Safe Operating Area

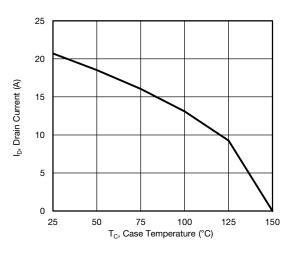


Fig. 10 - Maximum Drain Current vs. Case Temperature

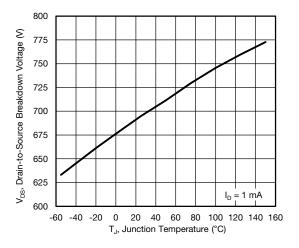


Fig. 11 - Temperature vs. Drain-to-Source Voltage

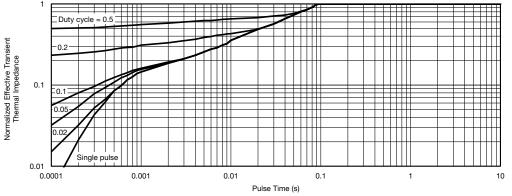
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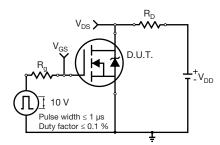


Fig. 13 - Switching Time Test Circuit

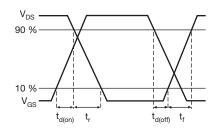


Fig. 14 - Switching Time Waveforms

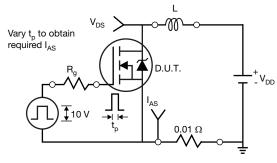


Fig. 15 - Unclamped Inductive Test Circuit

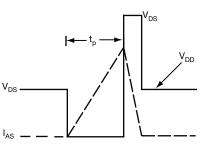


Fig. 16 - Unclamped Inductive Waveforms

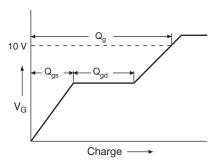


Fig. 17 - Basic Gate Charge Waveform

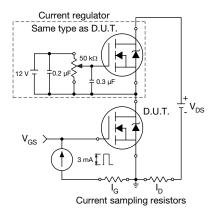


Fig. 18 - Gate Charge Test Circuit

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Peak Diode Recovery dV/dt Test Circuit

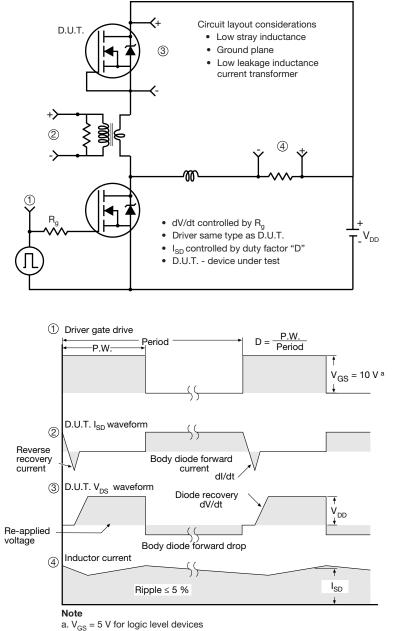


Fig. 19 - For N-Channel

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